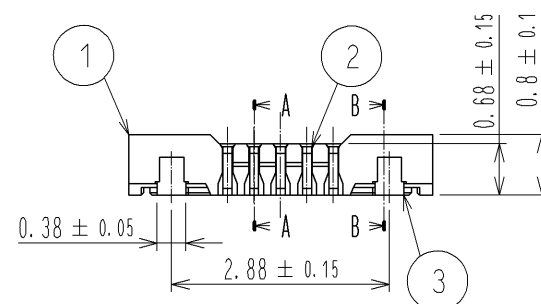


NOTE) 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX

2 ➤ CONTACT PLATING SPECIFICATIONS.

CONTACT AREA : GOLD 0.05 μ m MIN

SMT LEAD : GOLD 0.05 μ m MIN

UNDERPLATING : NICKEL 1 μ m MIN

(SURFACE : SEALING)

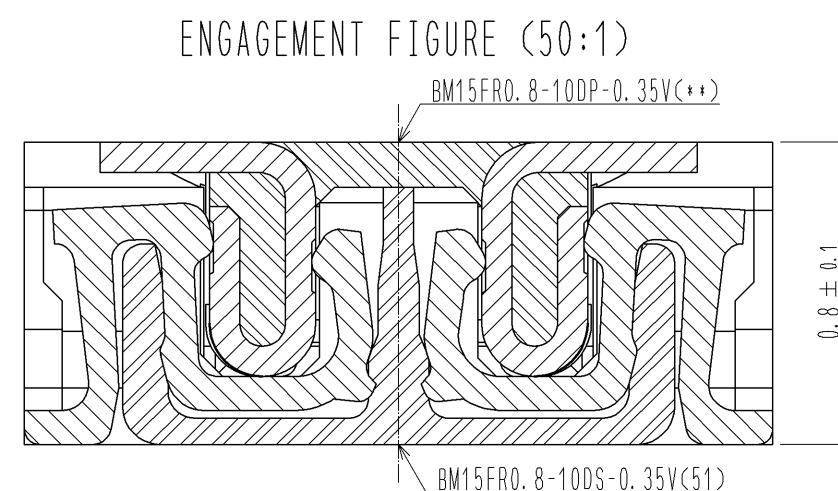
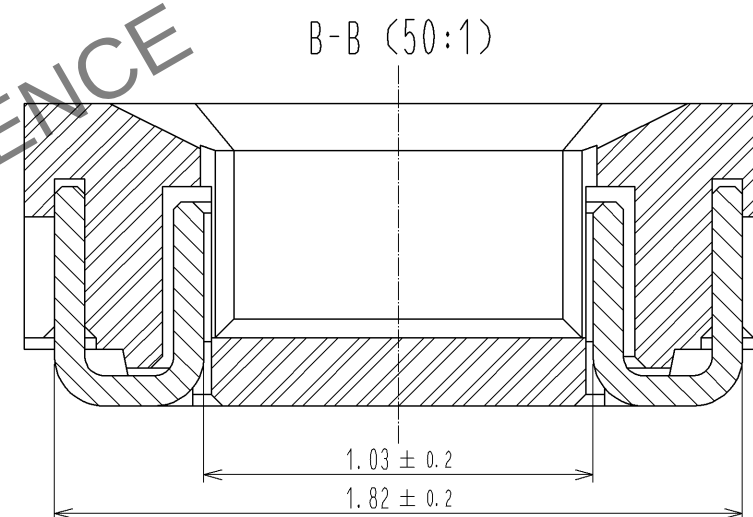
3 ➤ REINFORCED METAL FITTINGS LOCK

SMT LEAD : GOLD 0.05 μ m MIN

UNDERPLATING : NICKEL 1 μ m MIN

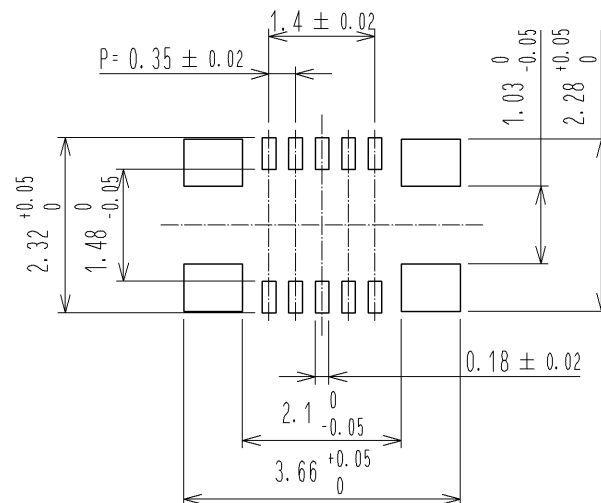
(SURFACE : SEALING)

4 ➤ CAV NO. AND HRS MARK MAY BE INDICATED IN APPROX POSITION SHOWN.

[illegible]

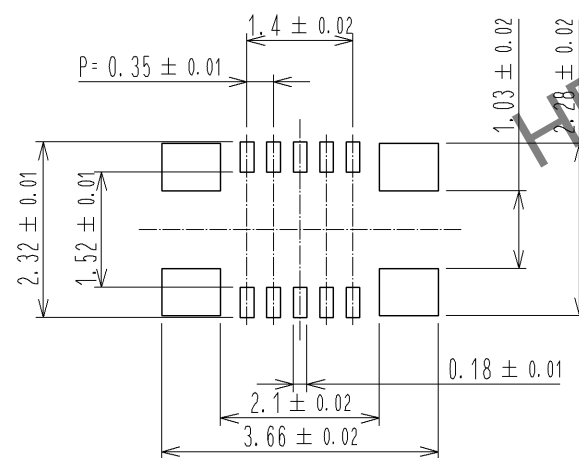
Jul.1.2024 Copyright 2024 HIROSE ELECTRIC CO., LTD. All Rights Reserved.
In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.

◆ RECOMMENDED PCB LAYOUT

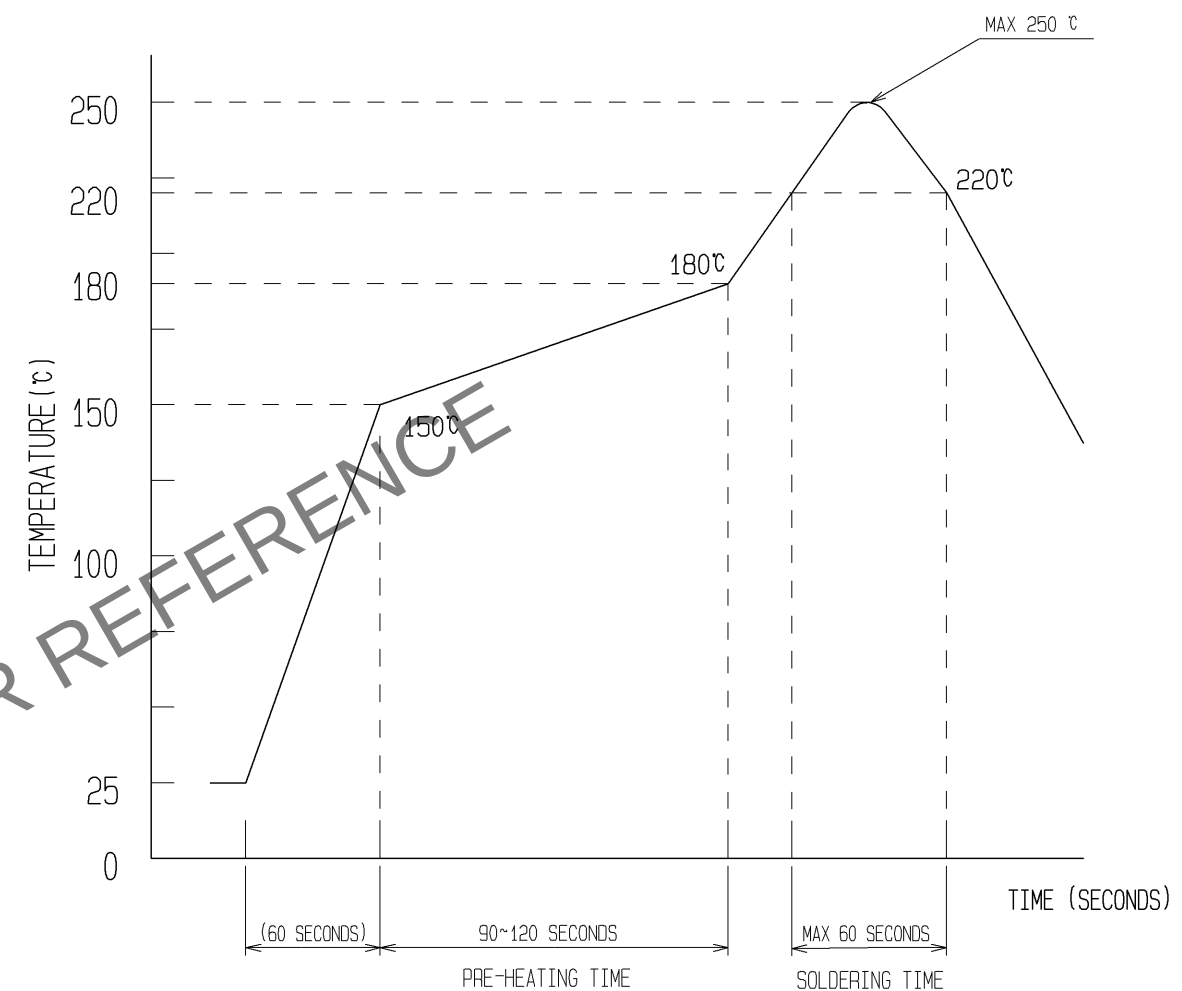


◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : $100 \mu\text{m}$



5 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW

NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME

DURATION ABOVE 220°C: 60 SEC. MAX.
(PEAK TEMPERATURE: 250°C MAX)

2) PRE-HEAT TIME

PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 sec.

5 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC3-355885-01
PART NO.	BM15FR0.8-10DS-0.35V<51>
CODE NO.	CL673-1225-5-51

2/3

Jul.1.2024 Copyright 2024 HIROSE ELECTRIC CO., LTD. All Rights Reserved.
In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.

